

XTX-BSW

Thermal Image Analysis Report

Summary	<input checked="" type="checkbox"/> Pass <input type="checkbox"/> Fail <input type="checkbox"/> Pass with Deviation Comment:			
	Test Result Summary			
	Critical	Major	Minor	Enhancement
Defect Found	0	0	0	0
Defect Unsolved	0	0	0	0

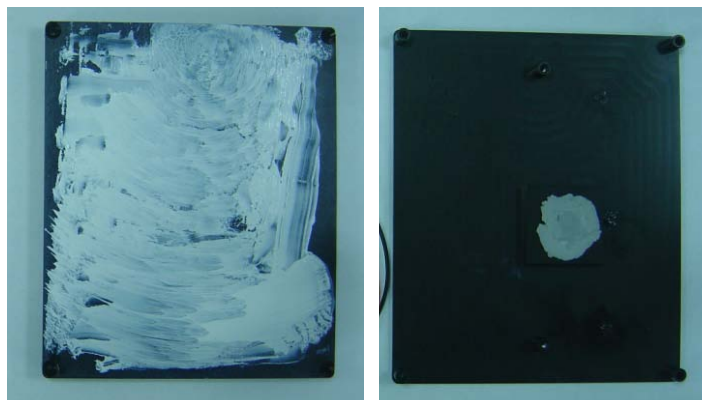
Issue date	QE Manager	Test Engineer
2016 / 04 / 01	KJ Wnag	Juno Cheng

Sample Configuration & Quantity Under Test

- Model name :XTX-BSW A0.2
- CPU Board : XTX-BSW A0.2
- CPU : Intel® Processor N3710 @ 1.6 GHz
- Memory : AAEON 4GB / DDR3L 1600 / SEC K4B4G0846D
- 2.5" SATA : Western Digital WD800BEVT / 80GB
- BIOS : R0.6 (XBSWAM06) (01/27/2016)
- Test Software : Windows 8.1 / Run Run BurnIn test 8.1 Pro(1013)
- ATX Power : DSA400P-C
- Cooler (17592XCV00) :



- Heat spreader (M16XBSW000) :



Thermal Image Analysis

1. Test Date: 2016-04-01

2. Test Product: XTX-BSW

3. Test Site: AAEON QE Dept.

4. Temperature Measurement:

4.1. 40 Channel Thermal Recorder:

4.1.1 YOKOGAWA Inc,

4.2.2 Model: DA100-13-1D

Date of Calibration: 2015/09/10

Serial Number: 12A323190

4.2. IR Scanner: Infrared Camera

4.2.1 NEC Avio Infrared Technologies Co., Ltd.

4.2.2 Model: Thermo GEAR G100W2-D

Date of Calibration: 2015/12/01

Serial Number: 1051444

5. Test Condition:

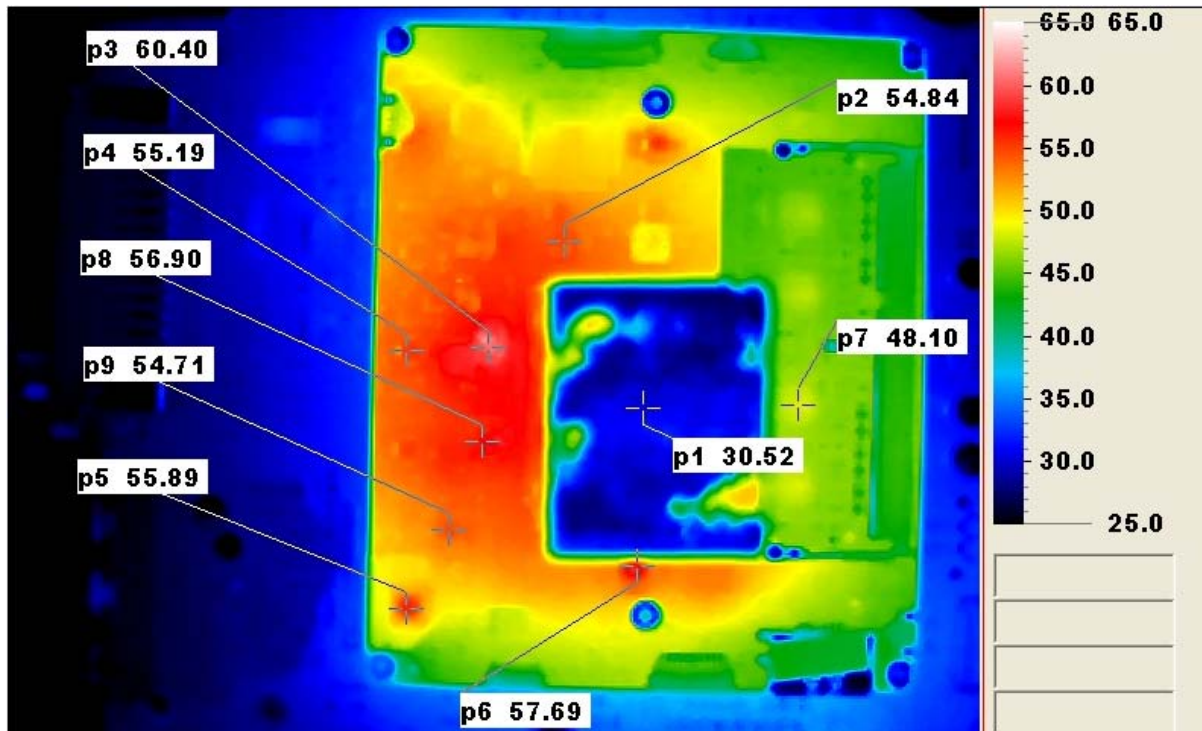
Test by DA-100: 25.0°C with Cooler + Heat spreader

6. Take Picture Time:

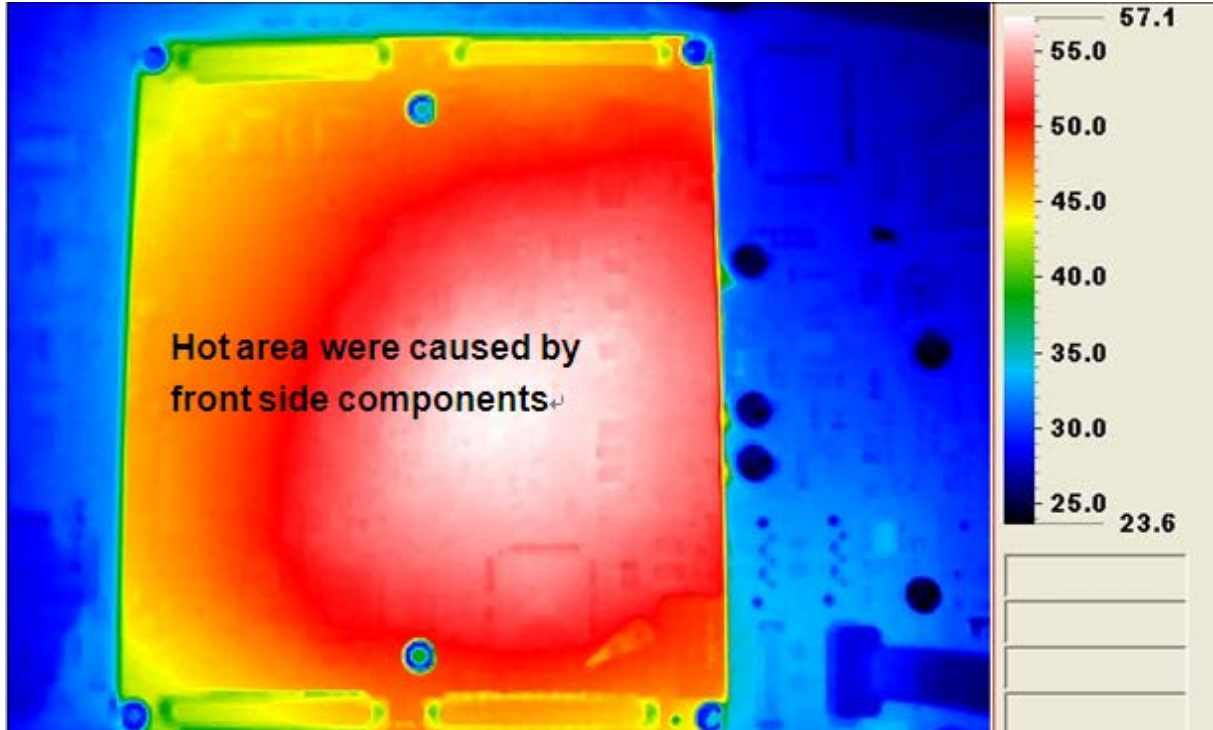
After power on 2 hours

Temperature Profile Test:

Component Side:

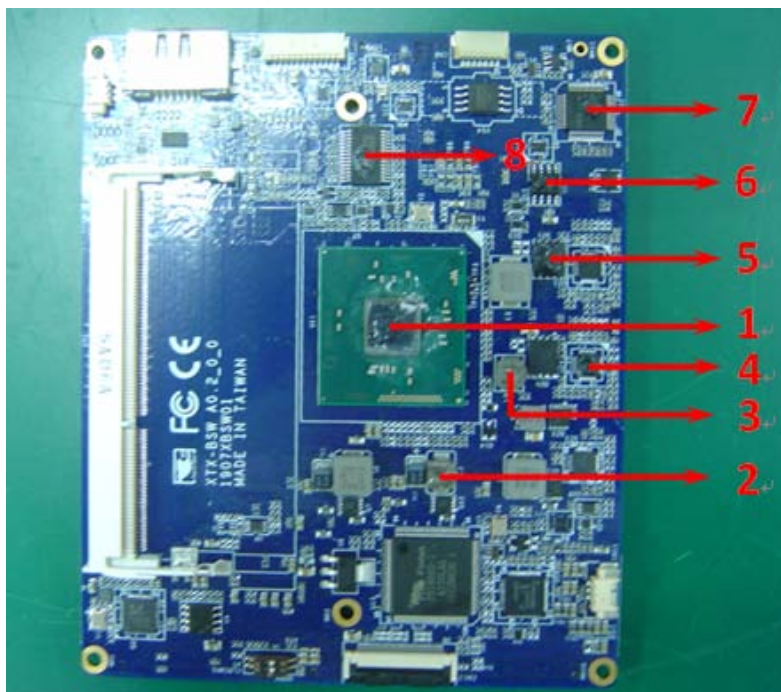


Back Side



Terminal Recorder:

Measuring Thermal Couple Position :



Using YOKOGAWA / DARWIN DA100-100-13-1D test

Point	Position	Describe	Tc (*1) (°C)	TAT(*2)		TPT(*3)	Note
				25.0°C	60°C		
1	U11	(TF)INTEL CPU.Braswell.N3710.2.56GHz.BGA1170P.	90	32.7	67.7		
2	L3	(TF)COIL.NEC/TOKIN.MPLCG0530L1R5	120	50.5	85.5		
3	L6	(TF)COIL.SMD.NEC/TOKIN.MPLCG0530LR22	120	58.5	93.5		
4	U24	(TF)IC.Signle-Phase Controller NCP81241MNTXG	100	49.5	84.5		
5	Q21	(TF)N-MOSFET. SMD.ON.NTMFD4C50NT1G	125	50.7	85.7		
6	U19	(TF)IC.LDO Linear Regulator.SMD.RICHTEK.RT9025-25PSP	100	48.7	83.7		
7	U22	(TF)IC.LQFP 48P.SMD.REALTEK.ALC892-CG	100.5	51.0	86.0		
8	U9	(TF)IC.SMD SSOP 28P.Clock Buffer.ICS.ICS9DB104FLFT	115	53.1	88.1		
9		DIMM	95	47.0	82.0		

Note(*):

- "Tc" indicates the component's case maximum temperature value specified in its datasheet.
- "TAT" indicates the actual measured temperature under product specification.
- "TPT" indicates the predicted temperature under 25°C working environmental.
- Judgment Criteria:**
 - **Fail** : $T_m > T_c + 5^\circ\text{C}$; The measured value is over specification plus margin.
 - **Margin** : $T_c + 5^\circ\text{C} > T_m > T_c - 10^\circ\text{C}$; The measured value is within specification with margin.
For FANLESS system application, it is strongly recommended to add thermal dissipation design for better reliability.
 - **Pass** : $T_m < T_c - 10^\circ\text{C}$; The measured value is with safety margin.
- RTC battery avoid to put on heat position.** Please do not exceed battery temperature specification.